



## SCANNING ELECTRON MICROSCOPE (SEM) INSPECTIONS

MIL-STD 883 Method 2018

**PURPOSE.** This method provides a means of judging the quality and acceptability of device interconnect metallization on non-planar oxide integrated circuit wafers or dice. SEM inspection is not required on planar oxide interconnect technology such as chemical mechanical polish (CMP) processes. It addresses the specific metallization defects that are batch process orientated and which can best be identified utilizing this method. Conversely, this method should not be used as a test method for workmanship and other type defects best identified using method 2010.

### Test Results

Part Type	Description	Test Condition	Sample Size	Date	Results
MM2K-0530LCH-2	MMIC Mixer RF 5-30 GHz	-	4	04/20/18	Pass
MM1K-1140HCH-2	MMIC Mixer RF 11 - 40 GHz	-	4	11/22/17	Pass

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